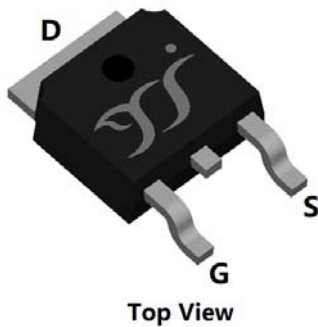
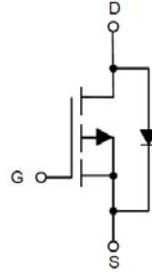
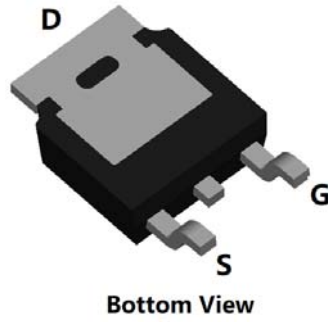


P-Channel Enhancement Mode Field Effect Transistor



TO-252



Product Summary

- V_{DS} -100V
- I_D -15A
- $R_{DS(on)}$ (at $V_{GS}=-10V$) <math>< 120m\Omega</math>
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Split gate trench MOSFET technology
- Low $R_{DS(on)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Moisture Sensitivity Level 1
- Part no. with suffix "Q" means AEC-Q101 qualified

Applications

- Power management
- Portable equipment
- 12V, 24V and 48V Automotive systems

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	-100	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_A=25^\circ C$	I_D	-2.5	A
	$T_A=100^\circ C$		-1.5	
	$T_C=25^\circ C$		-15	
	$T_C=100^\circ C$		-9.5	
Pulsed Drain Current ^A		I_{DM}	-35	A
Avalanche energy ^B		EAS	72	mJ
Total Power Dissipation ^C	$T_A=25^\circ C$	P_D	1.4	W
	$T_A=100^\circ C$		0.5	
	$T_C=25^\circ C$		50	
	$T_C=100^\circ C$		20	
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^\circ C$



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■ Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^D	Steady-State	$R_{\theta JA}$	70	85	°C/W
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	1.9	2.5	

■ Ordering Information (Example)

PREFERED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJD15GP10HQ	F1	YJD15GP10H	2500	/	25000	13" reel

A. Repetitive rating; pulse width limited by max. junction temperature.

B. $T_J=25^{\circ}\text{C}$, $V_{DD}=-50\text{V}$, $V_G=-10\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_D=-17\text{A}$.

C. P_d is based on max. junction temperature, using junction-case thermal resistance.

D. The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.



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■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-100	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-100V, V_{GS}=0V$	-	-	-1	μA
		$V_{DS}=-100V, V_{GS}=0V, T_J=150^\circ\text{C}$	-	-	-100	
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-2	-2.7	-4	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-15A$	-	90	120	m Ω
Diode Forward Voltage	V_{SD}	$I_S=-10A, V_{GS}=0V$	-	-0.9	-1.2	V
Gate resistance	R_G	$f=1\text{MHz}$	-	14	-	Ω
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=-25V, V_{GS}=0V, f=1\text{MHz}$	-	920	-	μF
Output Capacitance	C_{oss}		-	150	-	
Reverse Transfer Capacitance	C_{rss}		-	8	-	
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=-10V, V_{DS}=-50V, I_D=-7.5A$	-	15.6	-	nC
Gate-Source Charge	Q_{gs}		-	5.45	-	
Gate-Drain Charge	Q_{gd}		-	2.9	-	
Reverse Recovery Charge	Q_{rr}	$I_F=-7.5A, di/dt=100A/\mu s$	-	97	-	nC
Reverse Recovery Time	t_{rr}		-	59.5	-	
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=-10V, V_{DS}=-50V, I_D=-7.5A$	-	9.6	-	ns
Turn-on Rise Time	t_r		-	34.5	-	
Turn-off Delay Time	$t_{D(off)}$		-	34.2	-	
Turn-off fall Time	t_f		-	45	-	



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Typical Electrical and Thermal Characteristics Diagrams

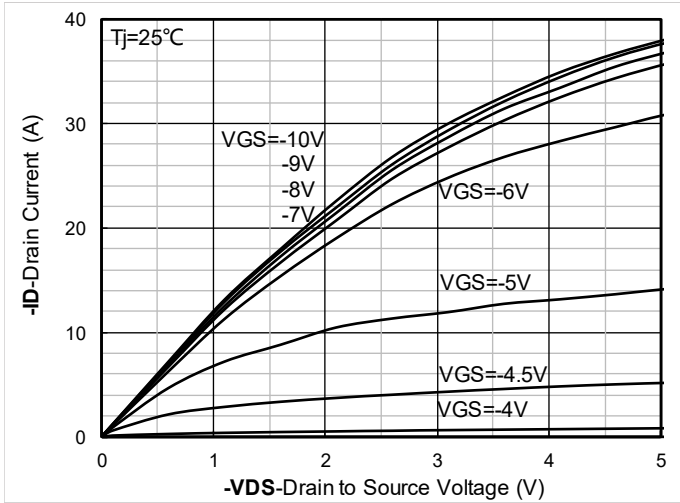


Figure1. Output Characteristics

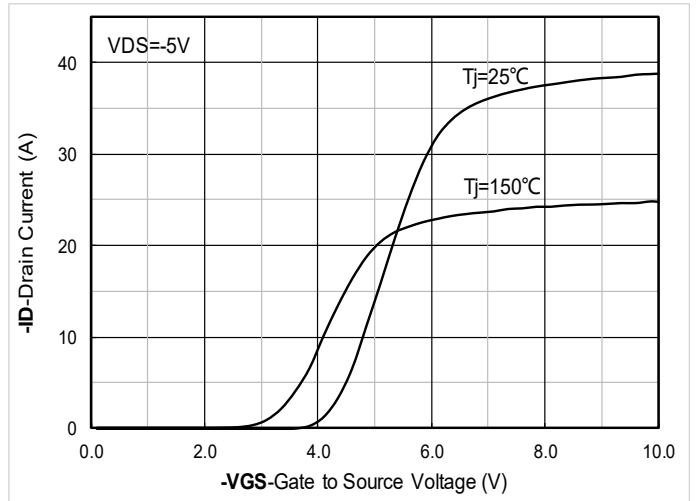


Figure2. Transfer Characteristics

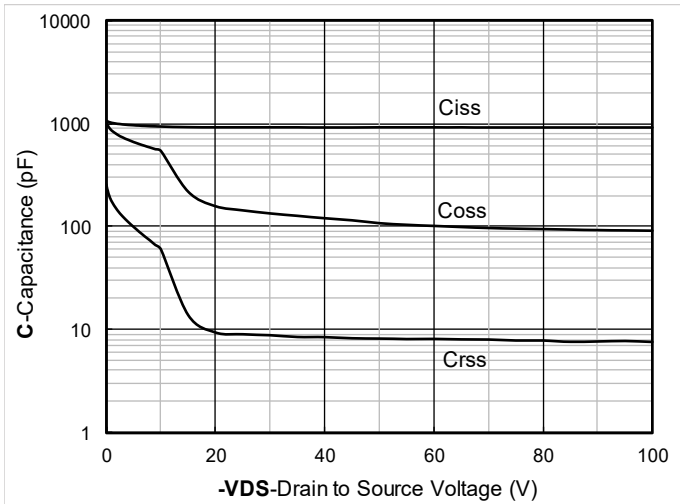


Figure3. Capacitance Characteristics

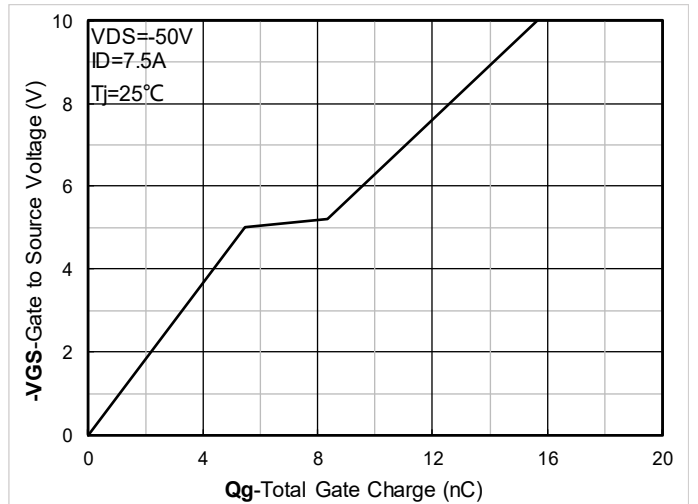


Figure4. Gate Charge

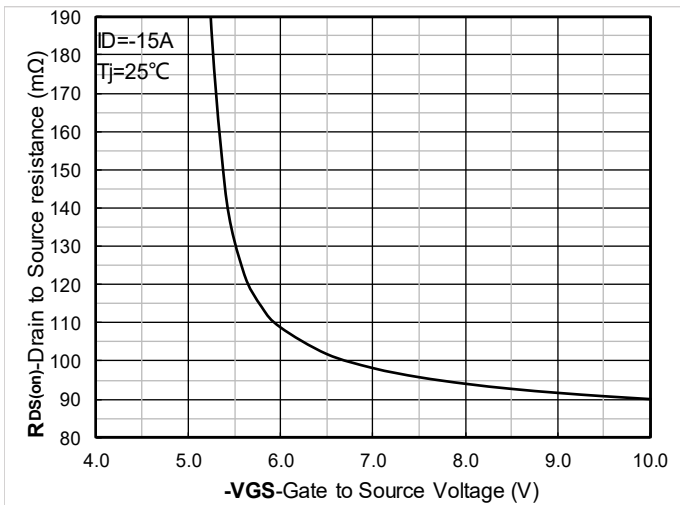


Figure5. On-Resistance vs Gate to Source Voltage

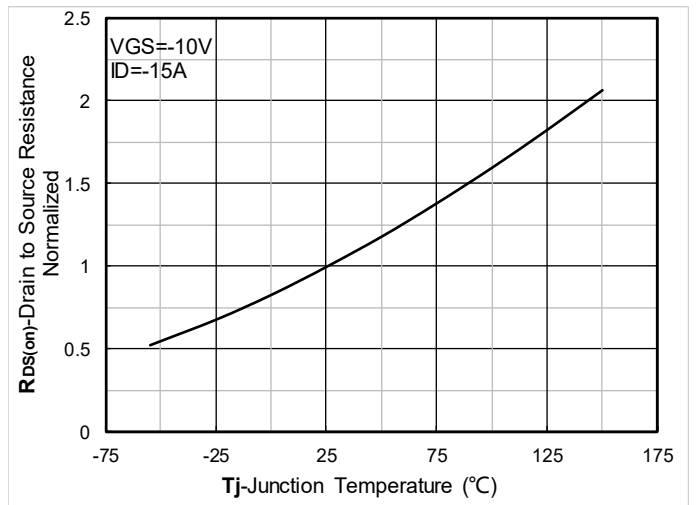


Figure6. Normalized On-Resistance



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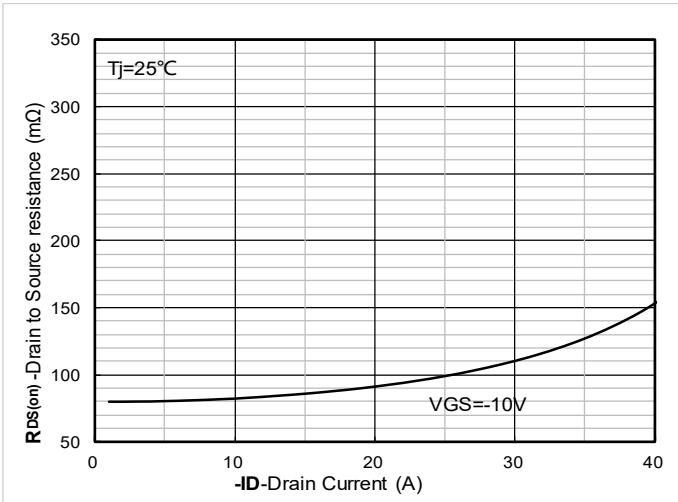


Figure7. $R_{DS(on)}$ VS Drain Current

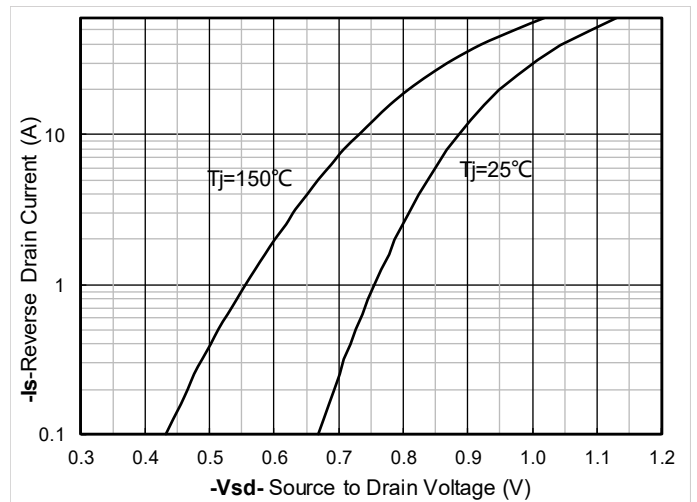


Figure8. Forward characteristics of reverse diode

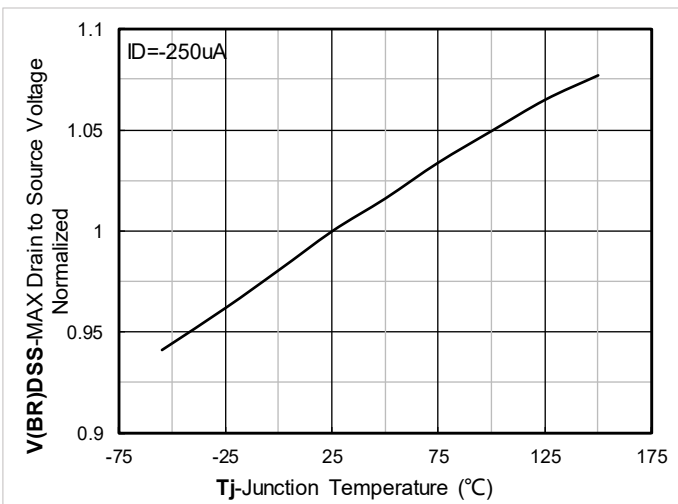


Figure9. Normalized breakdown voltage

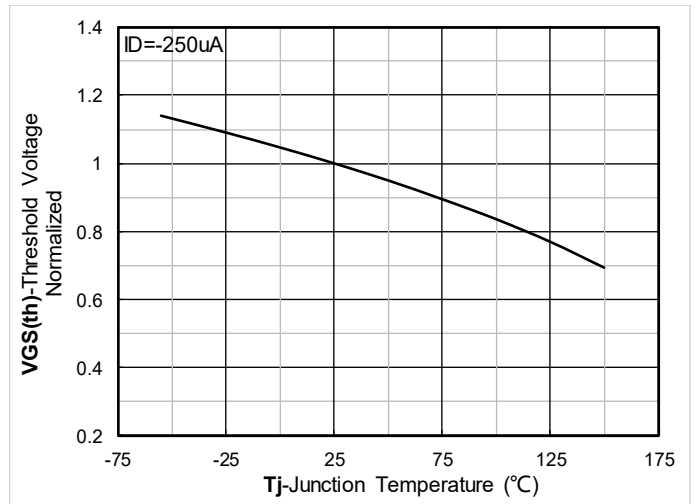


Figure10. Normalized Threshold voltage

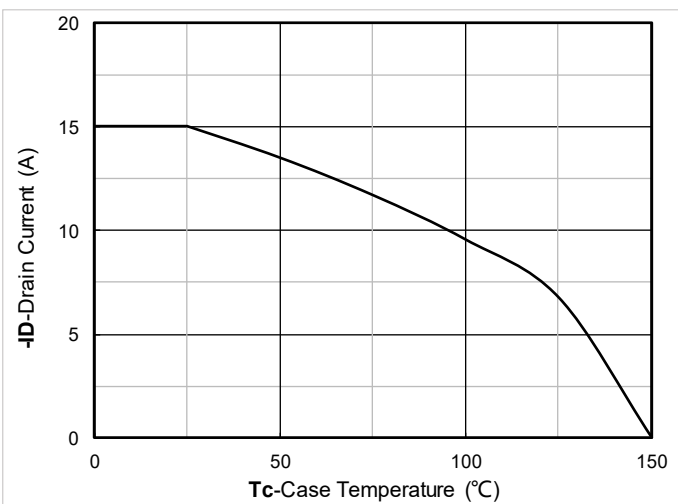


Figure11. Current dissipation

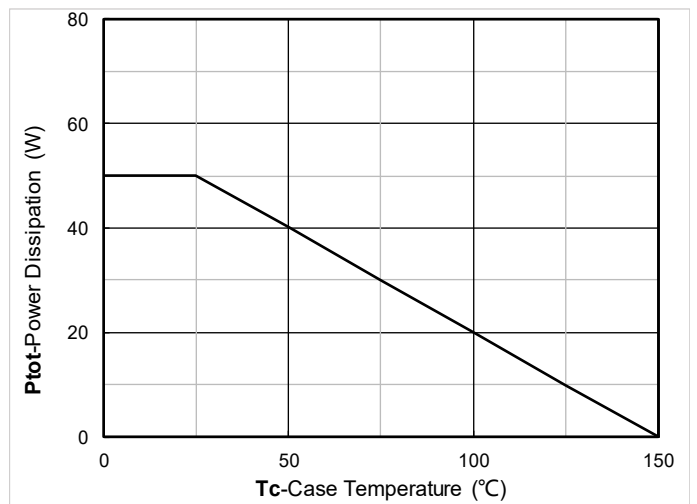


Figure12. Power dissipation



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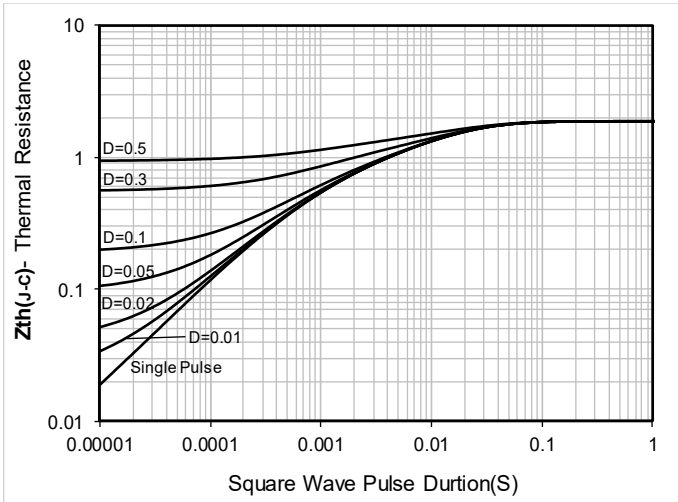


Figure13. Maximum Transient Thermal Impedance

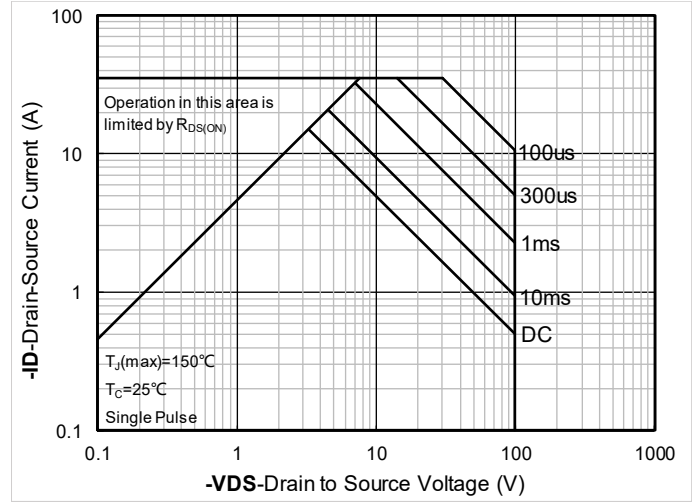
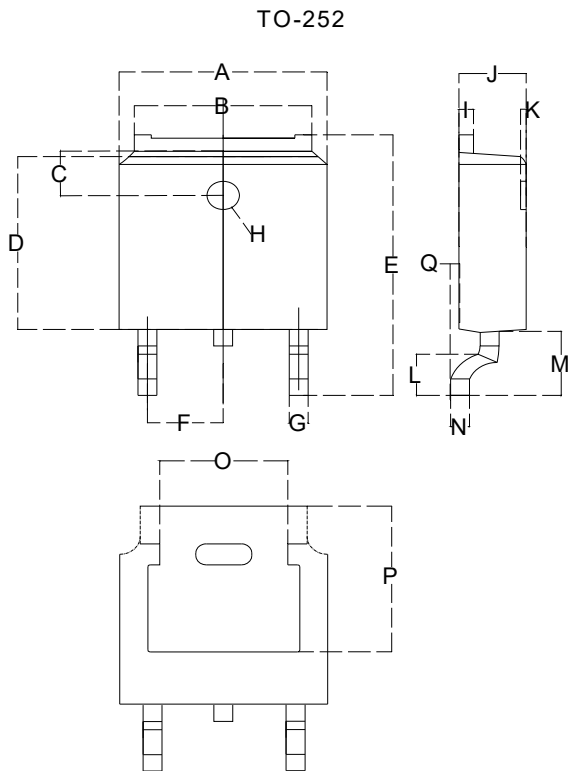


Figure14. Safe Operation Area



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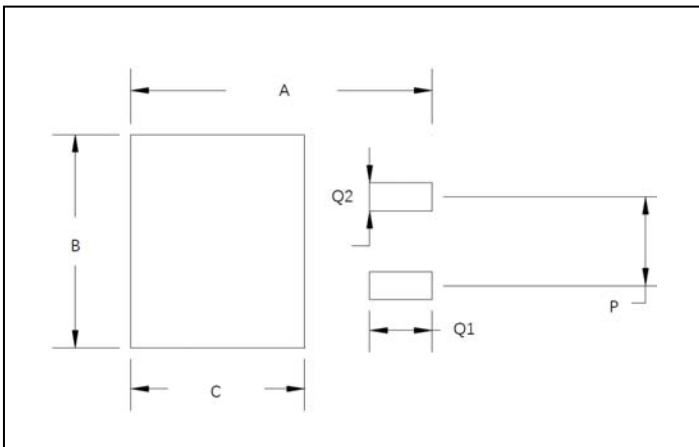
■ TO-252 Package information



TO-252		
Dim	Min	Max
A	6.500	6.700
B	5.100	5.460
C	1.400	1.800
D	6.000	6.200
E	10.000	10.400
F	2.166	2.366
G	0.660	0.860
H	Φ1.050	Φ1.350
I	0.460	0.580
J	2.200	2.400
K	0	0.300
L	0.890	2.290
M	2.730	3.080
N	0.430	0.580
O	4.20	4.95
P	5.15	5.45
Q	0	0.2

Dimensions in millimeters

■ Suggested Pad Layout



Dim	Millimeters
A	11.4
B	6.74
C	6.23
P	4.56
Q1	2.28
Q2	1.52



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Rev	Date	Revision
1.0	26-Jul-23	New release